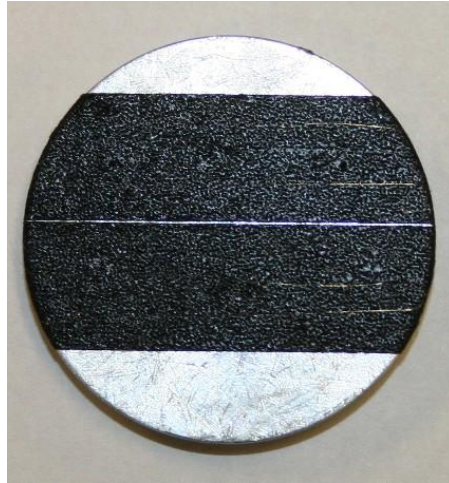


# Hall D Wire Characterization

## Samples F8-1 & F8-2

1. **Sample preparation:** ultrasonic cleaning in DI water for 45 minutes.
2. **Sample installation:** for SEM inspection wires were installed on a sample holder (diameter=36 mm) on 2 stripes of conductive carbon tape, 2 fragment of each sample per stripe (nomenclature: F8-1a, F8-1b and F8-2a, F8-2b).

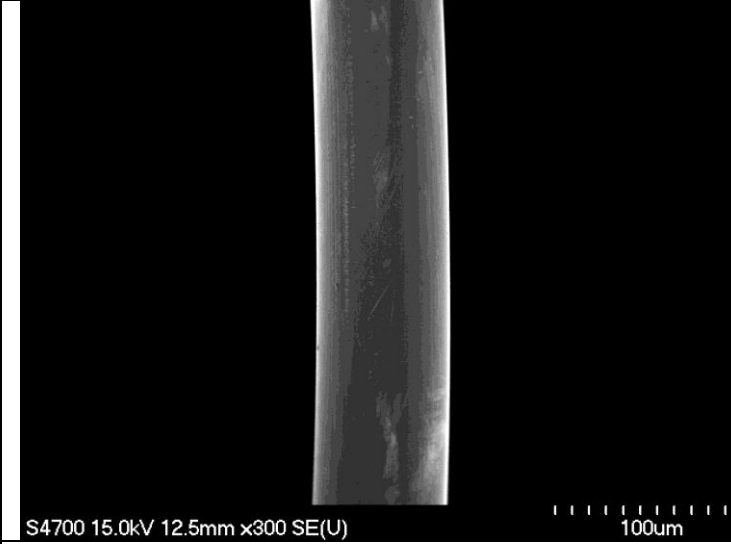
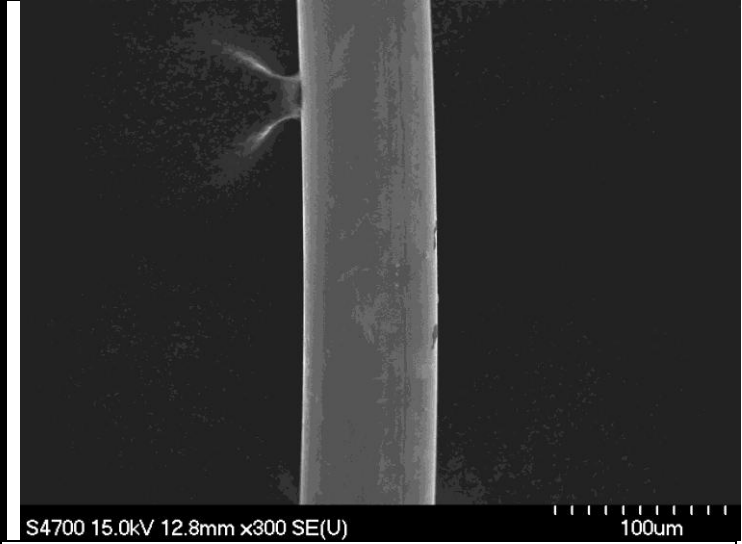
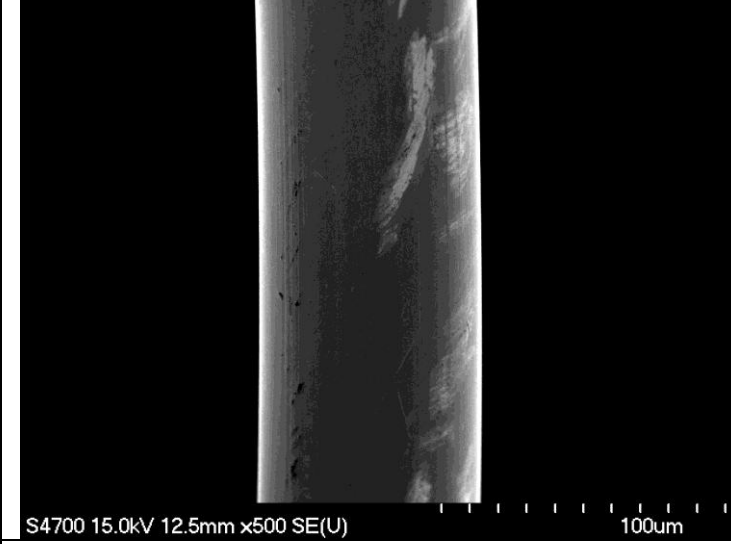
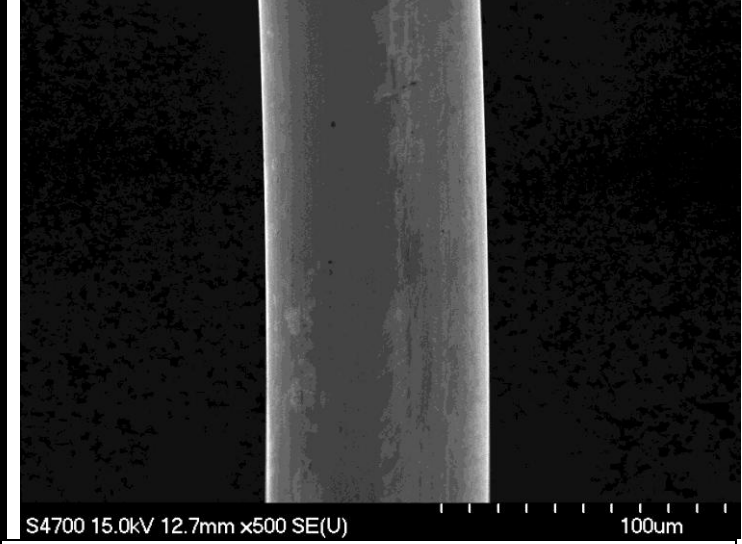


Pic1. Typical sample installation.

3. **Wire inspection:**
  - a) Each wire fragment was examined along its length (beginning at approximately 5mm from the sample holder edge and ending ~5mm before the opposite edge) at magnification of ~x600, at fast scan rate.
  - b) Images at designated magnifications (x300, x500, x800, x1000) were taken randomly along the sample length;
  - c) Images for the ovality measurements were taken at 1000x magnification in three points of each wire fragment: in the middle (approximately) and close to both ends;
  - d) Measurements of wire diameter, as visible on the images, were done using the Quartz PCI Image Management System, 3 measurements per image;
  - e) Additional images at various magnifications were taken at the points of interest (variations in sample topography, contaminated areas, etc.)
  - f) EDS analysis was performed on the most typical points of interest.

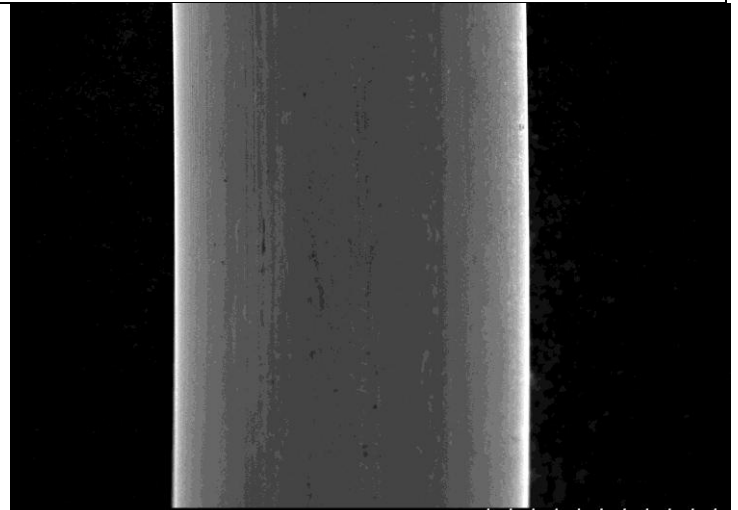
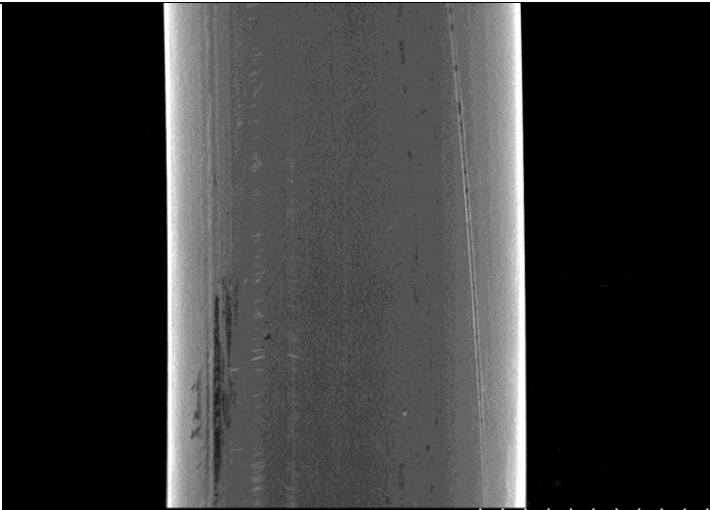
# Sample F8-1 A, B

## I. Images at designated magnifications

F8-1A-1	F8-1B-1
	
Magnification: 300x	Magnification: 300x
F8-1A-2	F8-1B-2
	
Magnification: 500x	Magnification: 500x

F8-1A-3

F8-1B-3

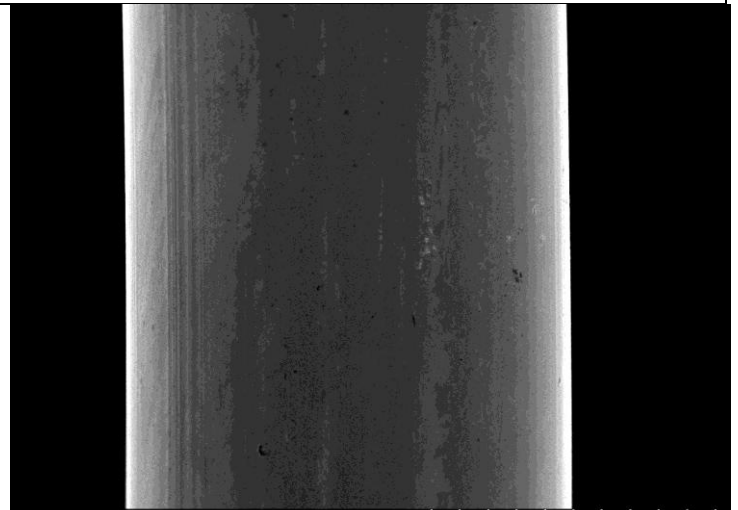
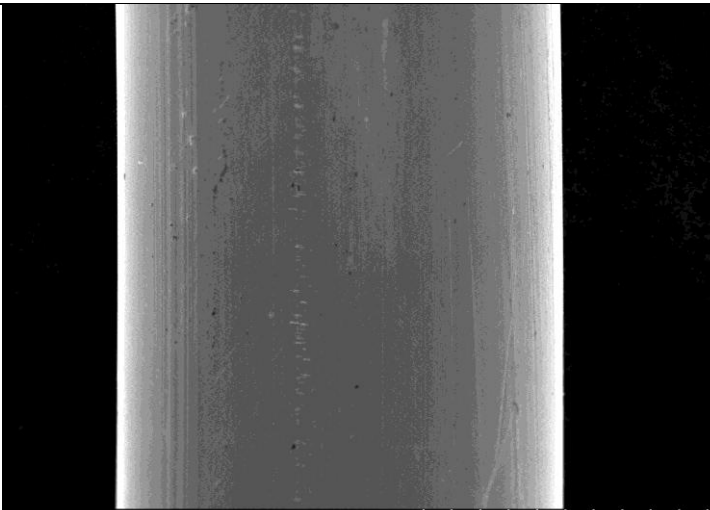


Magnification: 800x

Magnification: 800x

F8-1A-4

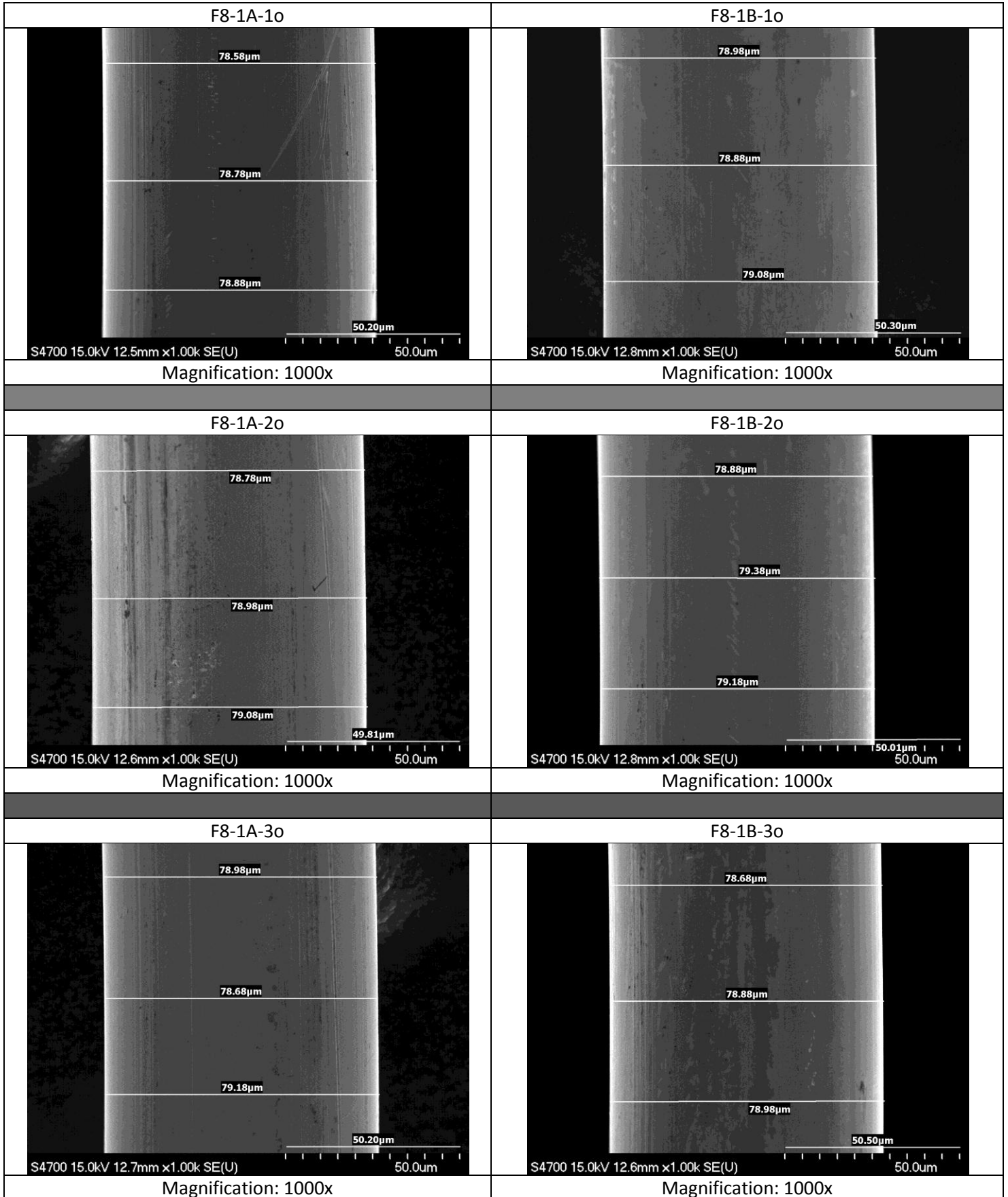
F8-1B-4



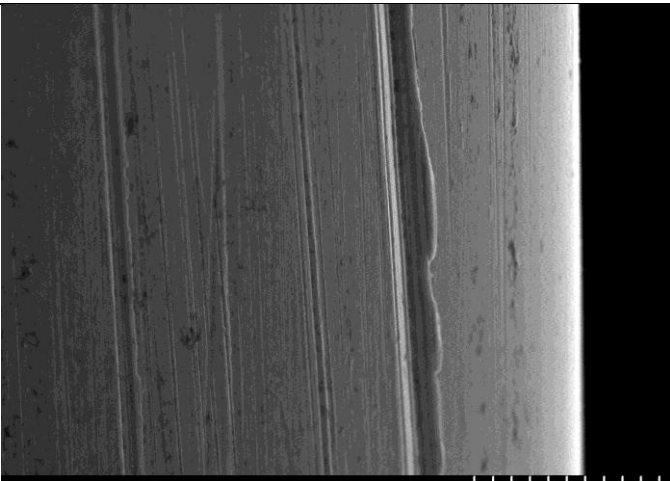
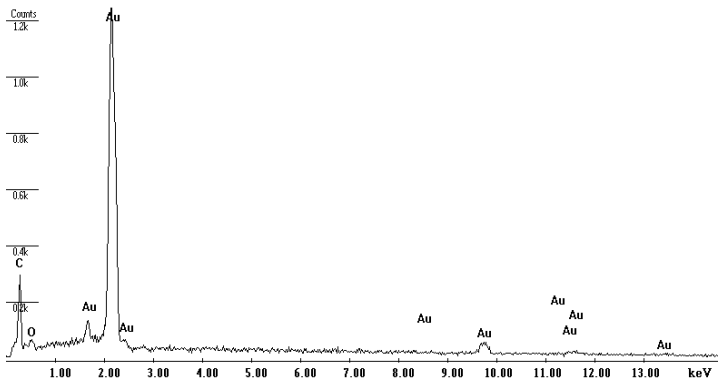
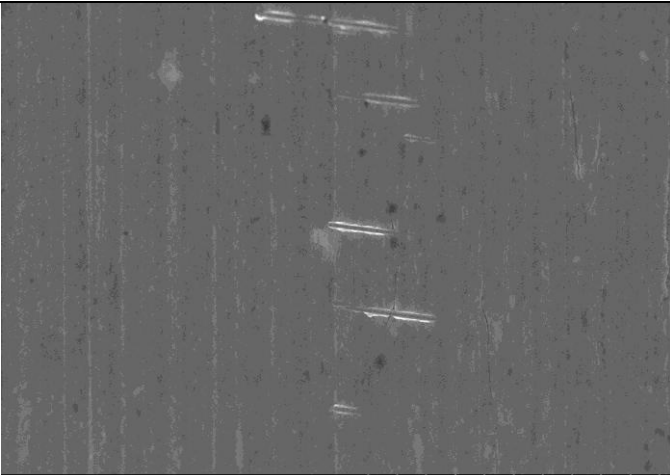
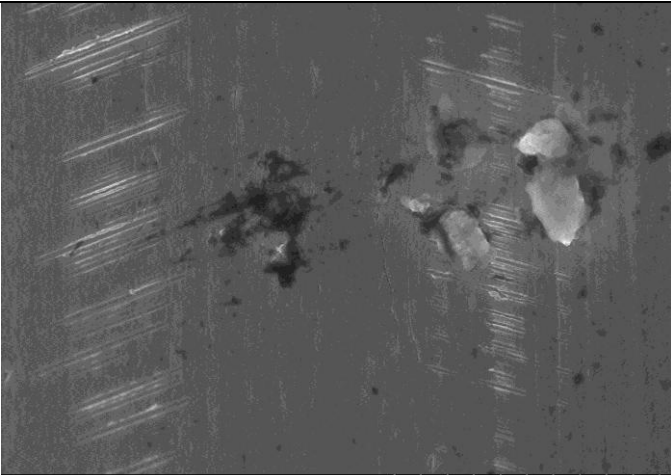

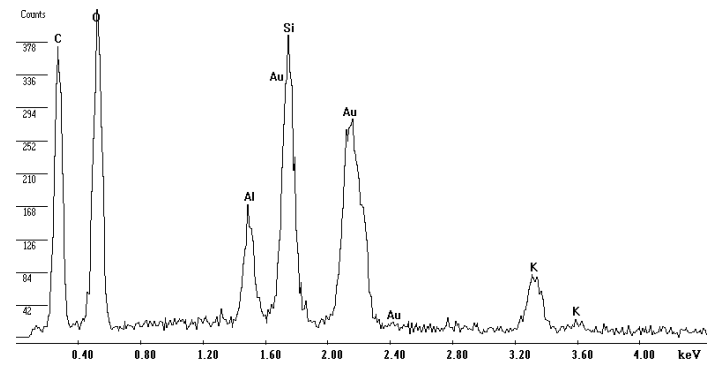
Magnification: 1000x

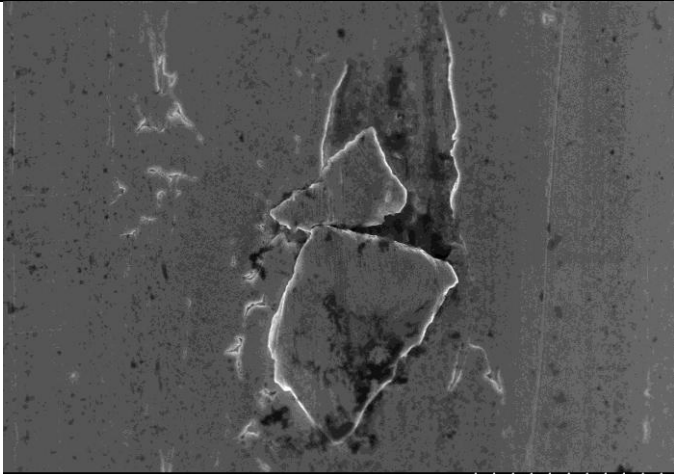
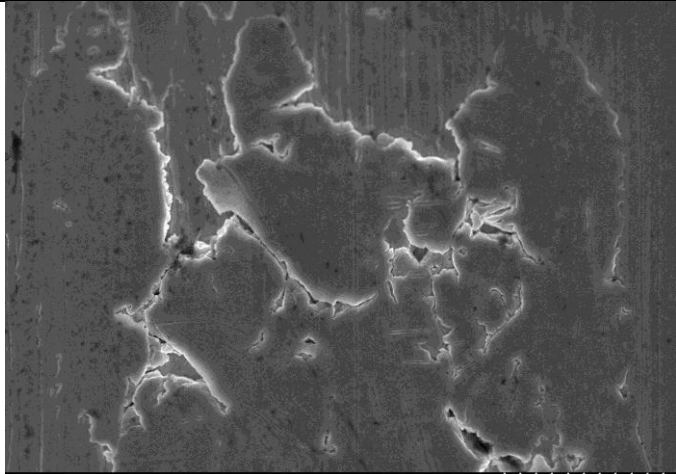
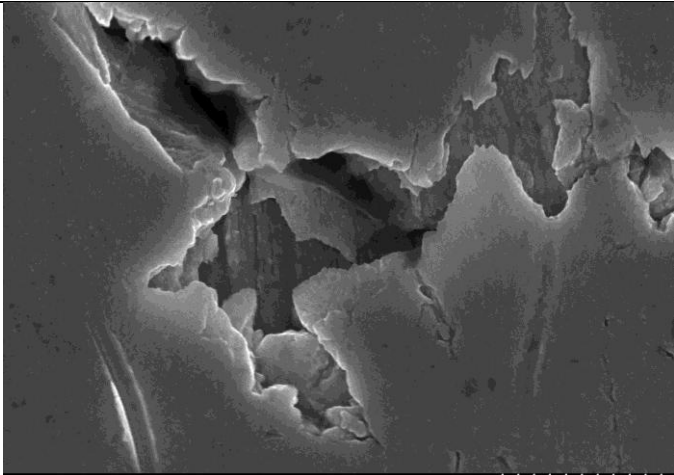
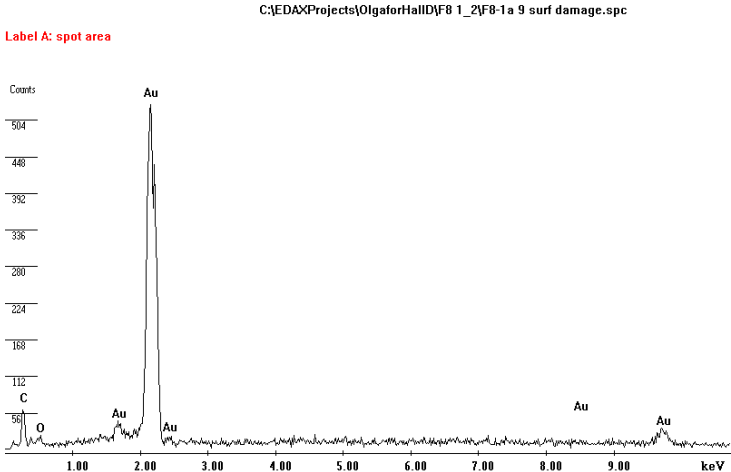
Magnification: 1000x

## II. Ovality Measurements



### III. Points of Interest

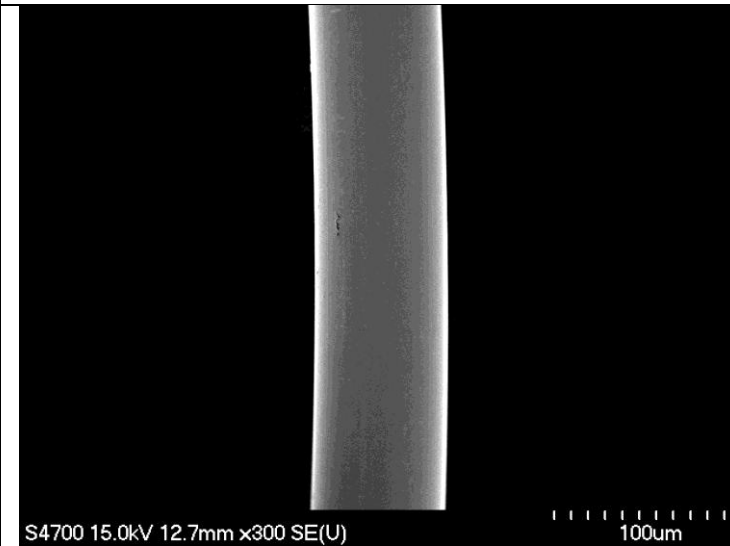
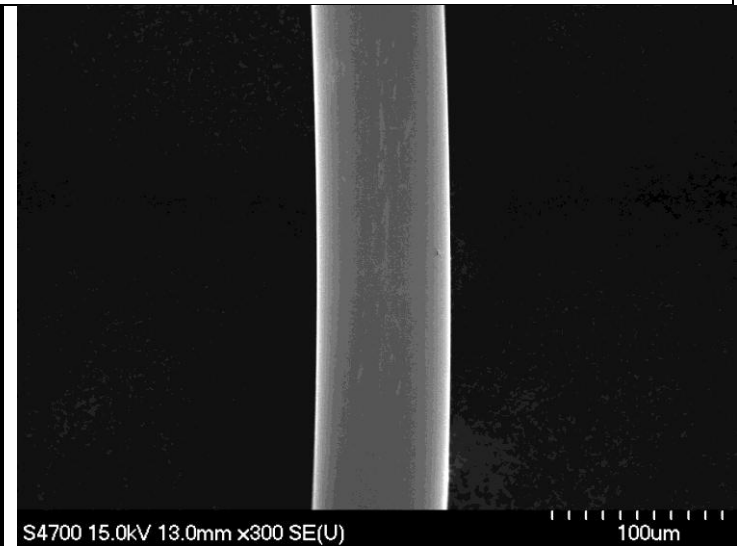
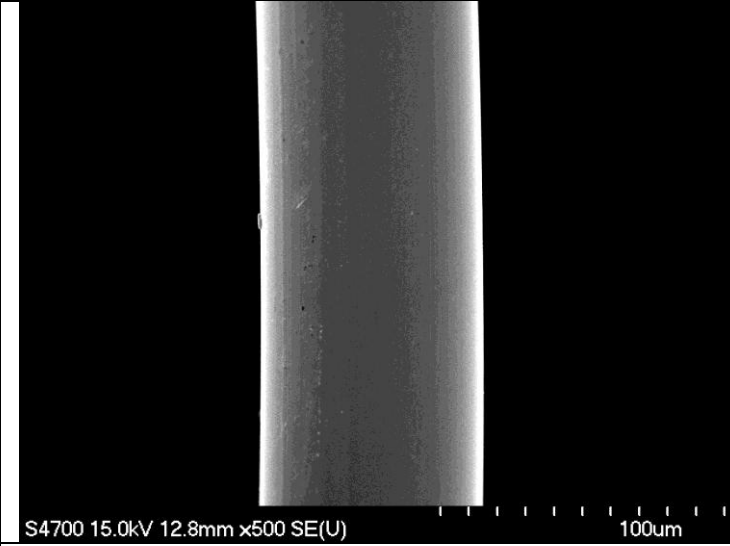
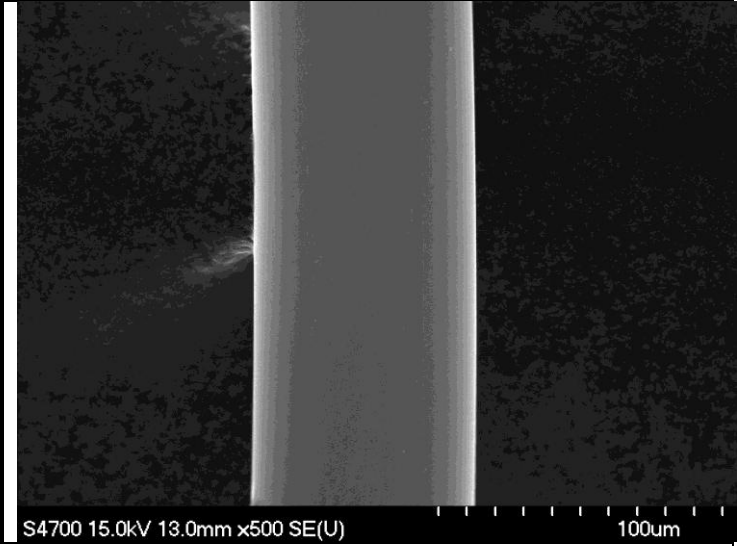
<p style="text-align: center;">F8-1A-6</p>  <p style="text-align: center;">Magnification: 6980x</p>	<p style="text-align: center;">F8-1A-6</p> <p style="text-align: center;">C:\EDAXProjects\OlgaforHallID\F8 1_2\F8-1a 6 scratch.spc</p> <p>Label A: spot area</p>  <p style="text-align: center;">EDS Analysis. Scratch. No Cu found.</p>
<p style="text-align: center;">F8-1A-4 Minor scratches.</p>	<p style="text-align: center;">F8-1A-8 Scratches and contamination.</p>
 <p style="text-align: center;">Magnification: 11000x</p>	 <p style="text-align: center;">Magnification: 10000x</p>
<p style="text-align: center;">F8-1B-5 Environmental contamination</p>	<p style="text-align: center;">F8-1B-5 Environmental contamination</p>
 <p style="text-align: center;">Magnification: 5990x</p>	<p style="text-align: center;">F8-1B-5 Environmental contamination</p> <p style="text-align: center;">C:\EDAXProjects\OlgaforHallID\F8 1_2\F8-1b 5 typical cont.spc</p> <p>Label A: spot area</p>  <p style="text-align: center;">EDS Analysis. Typical surface contamination</p>

<p>F8-1B-10 Surface damage</p>  <p>S4700 15.0kV 12.6mm x3.50k SE(U) 10.0um</p>	<p>F8-1B-7 Surface damage</p>  <p>S4700 15.0kV 12.6mm x6.00k SE(U) 5.00um</p>
<p>Magnification: 3500x</p>	<p>Magnification: 6000x</p>
<p>F8-1B-7 Surface damage. High mag</p>  <p>S4700 15.0kV 12.6mm x30.0k SE(U) 1.00um</p>	<p>F8-1B-7 Surface damage. High mag</p>  <p>C:\EDAX\Projects\OlgaforHallID\F8 1_2\F8-1a 9 surf damage.spc</p> <p>Label A: spot area</p> <p>Cents</p> <p>504</p> <p>448</p> <p>392</p> <p>336</p> <p>280</p> <p>224</p> <p>168</p> <p>112</p> <p>C</p> <p>56</p> <p>O</p> <p>Au</p> <p>Au</p> <p>Au</p> <p>Au</p> <p>Au</p> <p>keV</p>
<p>Magnification: 30000x</p>	<p>EDS Analysis. Surface damage. No Cu found.</p>

**Note:**

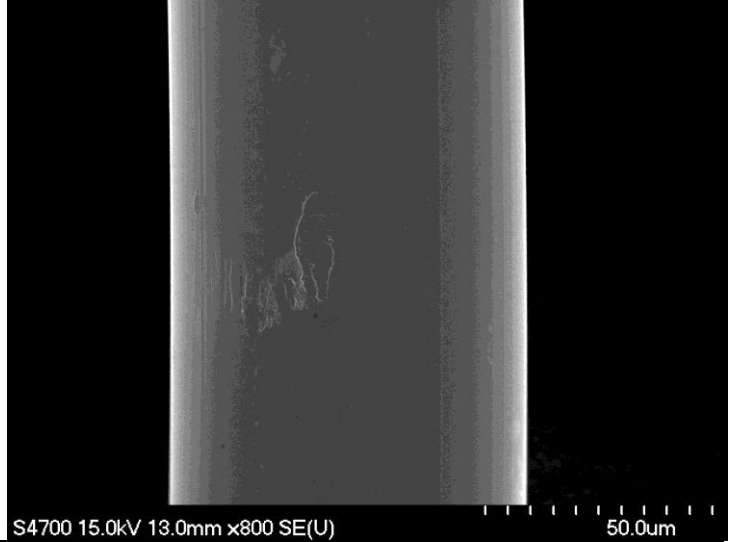
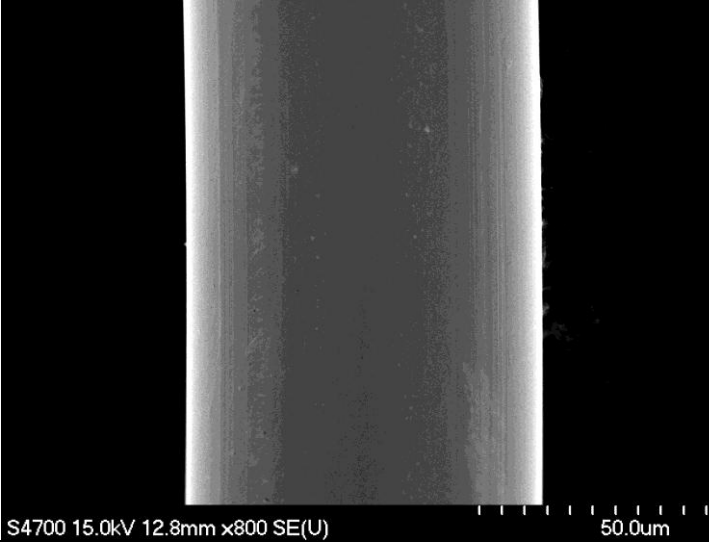
- 1) No traces of Cu within the damaged area were indicated by the EDS analysis (detection limit ~1%).

**Sample F8-2 A, B**  
Images at designated magnifications

F8-2A-1	F8-2B-1
	
Magnification: 300x	Magnification: 300x
F8-2A-2	F8-2B-2
	
Magnification: 500x	Magnification: 500x

F8-2A-3

F8-2B-3

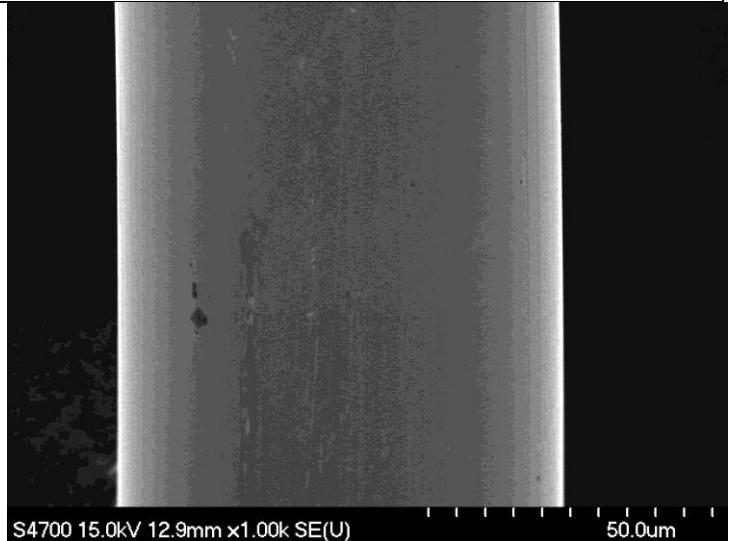
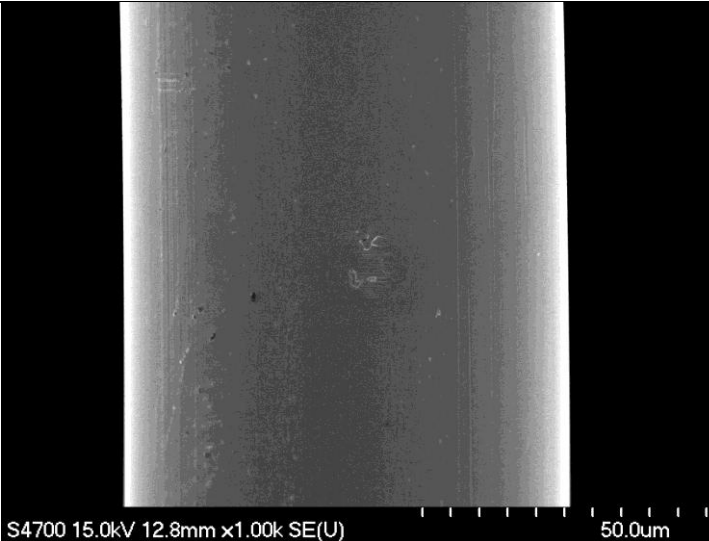


Magnification: 800x

Magnification: 800x

F8-2A-4

F8-2B-4

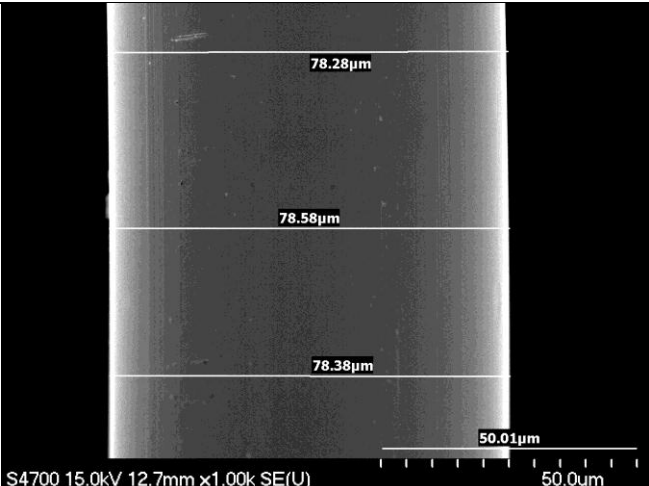
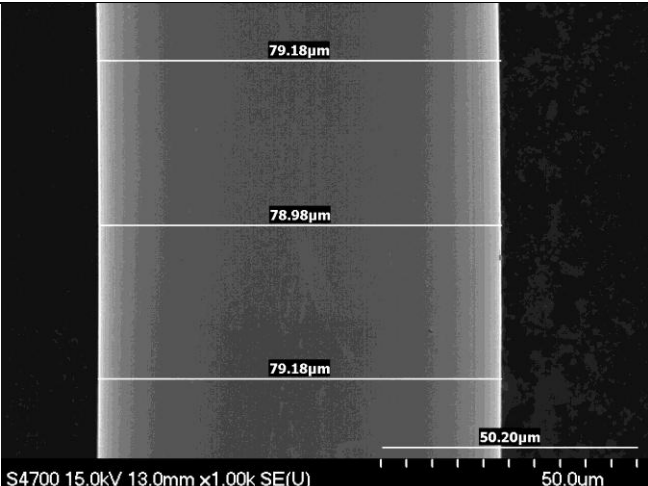
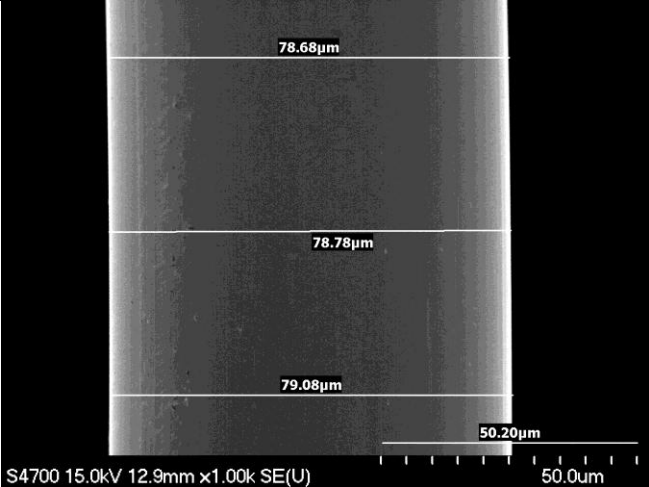
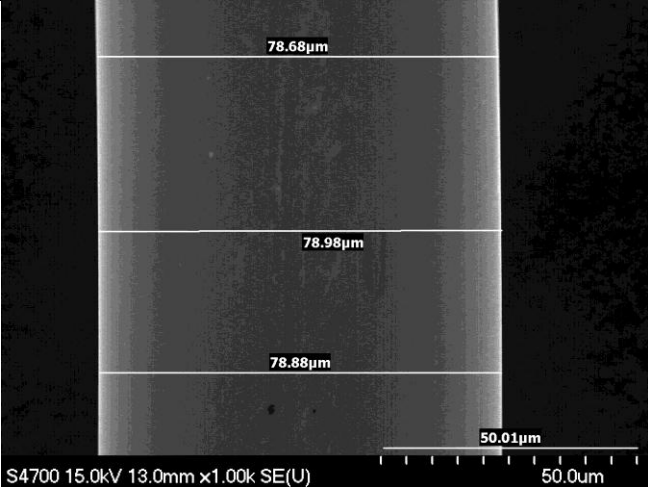
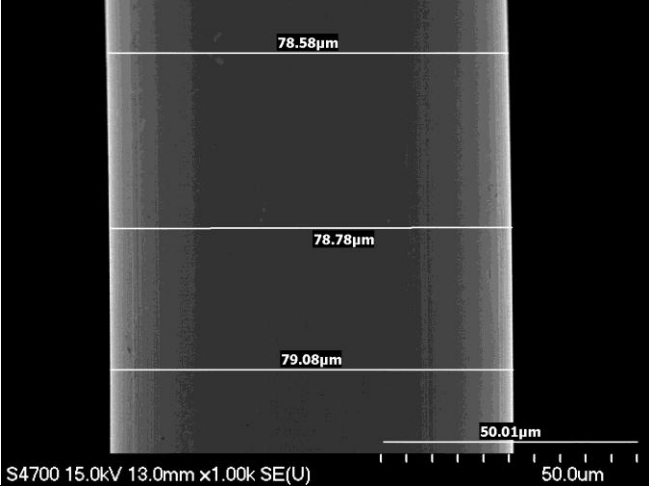
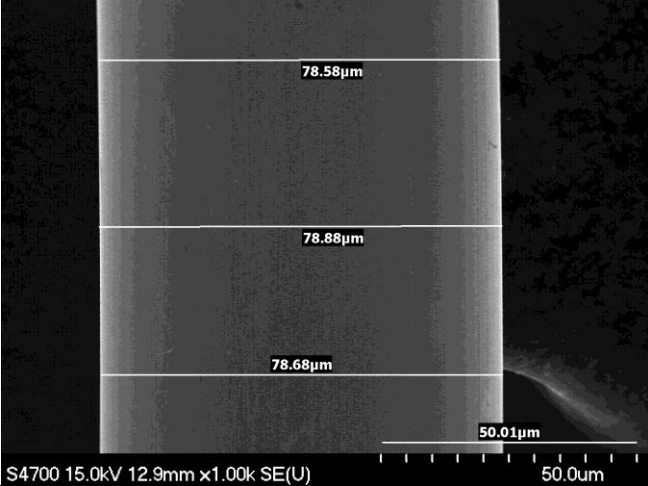


Magnification: 1000x

Magnification: 1000x

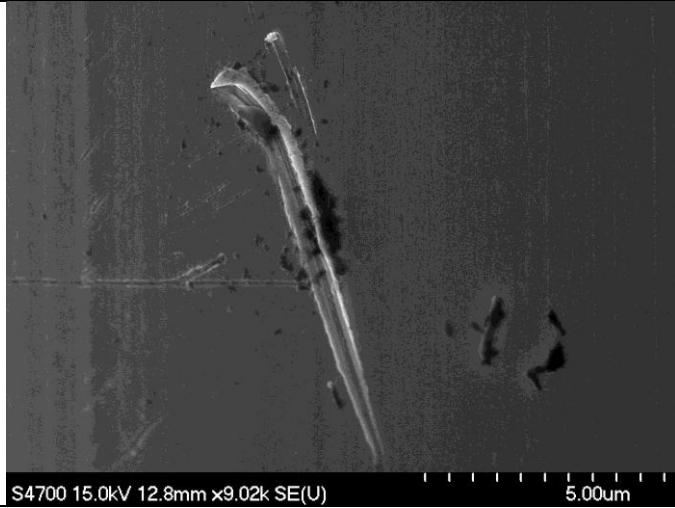


## II. Ovality Measurements

<p>F8-2A-1o</p>  <p>S4700 15.0kV 12.7mm x1.00k SE(U)</p> <p>Magnification: 1000x</p>	<p>F8-2B-1o</p>  <p>S4700 15.0kV 13.0mm x1.00k SE(U)</p> <p>Magnification: 1000x</p>
<p>F8-2A-2o</p>  <p>S4700 15.0kV 12.9mm x1.00k SE(U)</p> <p>Magnification: 1000x</p>	<p>F8-2B-2o</p>  <p>S4700 15.0kV 13.0mm x1.00k SE(U)</p> <p>Magnification: 1000x</p>
<p>F8-2A-3o</p>  <p>S4700 15.0kV 13.0mm x1.00k SE(U)</p> <p>Magnification: 1000x</p>	<p>F8-2B-3o</p>  <p>S4700 15.0kV 12.9mm x1.00k SE(U)</p> <p>Magnification: 1000x</p>

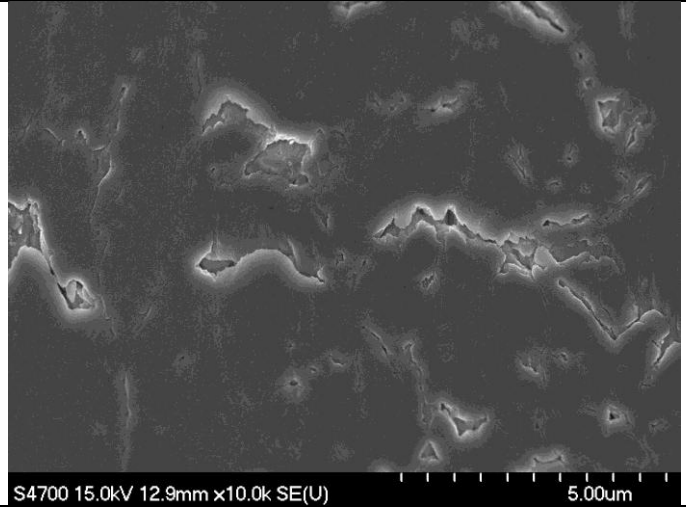
### III. Points of Interest

F8-2A-5 Scratch and contamination.



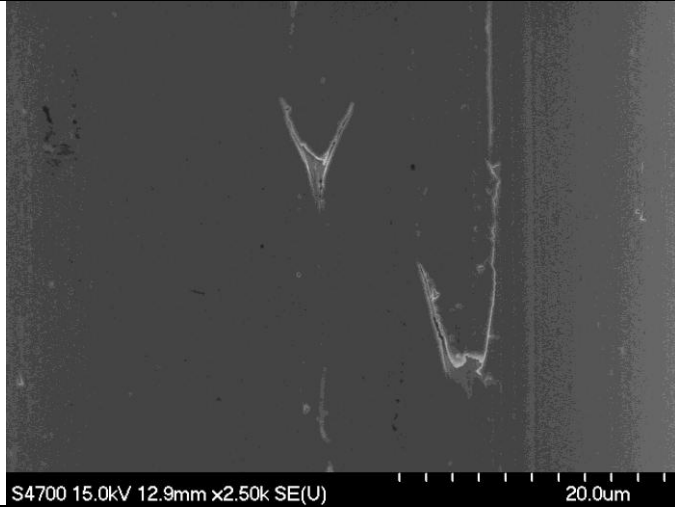
Magnification: 9020x

F8-2A-8 Surface damage.



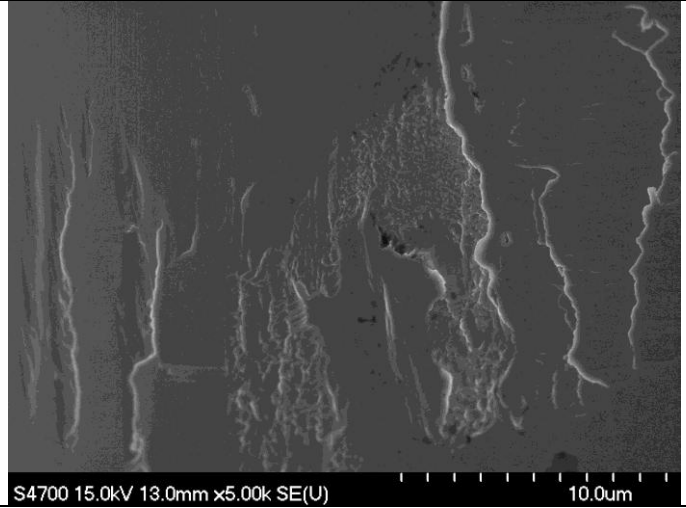
Magnification: 10000x

F8-2B-6 Surface damage.



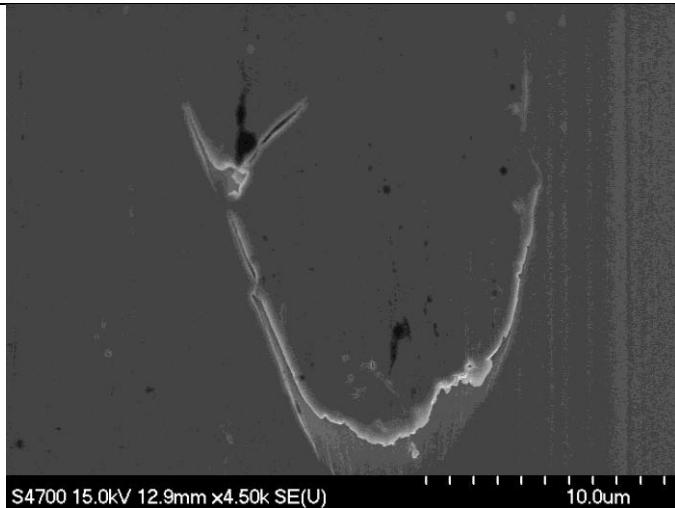
Magnification: 2500x

F8-2B-4 Surface damage.



EDS Analysis. Surface damage. No Cu.

F8-2B-7 Details of surface structure.



Magnification: 4500x

